METHOD OF FORMING BALL GRID ARRAY CONTACTS

ABSTRACT OF THE DISCLOSURE

The invention is a method for forming solder contact balls for a ball grid array semiconductor device. A sheet of solder (13)is stamped or etched to form an array (9) of solder preforms (14). The array (9) of preforms (14) is placed over a substrate (30) on which solder balls (32) are to be electrically connected to contact areas (14a). The array (9) of preforms (14) is aligned on the substrate (30), one preform (14) over a contact area (14a). The substrate (30) and preforms (14) are heated to cause the solder to reflow such that the surface tension of the reflowed solder of each preform forms a solder ball (32) over a contact area (14a).

Figure 2